

# LDS431RP

## 2.5V Shunt Ref/Amplifier

**Product Specification** 

Revision 1.8

May 12, 2008

### **General Description**

The LDS431RP is a three-terminal adjustable shunt regulator based on a highly stable bandgap reference and is an excellent replacement for standard TL431 references when used as a secondary feedback element in Switch Mode Power Supplies.

The LDS431RP meets all of the requirements of standard 431 the specifications that are needed to monitor the • secondary output voltage and provide the feedback signal to the primary through an opto-coupler. It is offered in both the very popular SOT23-3 and TO-92 packages.

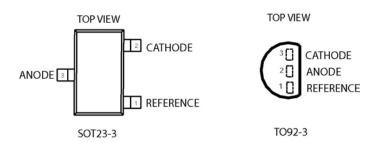
## **Applications**

- Power supply control loop
- Low TC voltage reference
- Power management applications

#### **Features**

- Programmable precise output voltage 2.5V to 15V
- Wide temp range: -40° to 85°C standard
- Improved stability with capacitive loads
- Low TC voltage reference
- Wide range of package options
- RoHS compliant

## **Pin Configuration**



## **Pin Descriptions**

Pin Name	Function
CATH	Output and supply terminal, must be greater than 2.5V for normal operation
REF	Input, nominally 2.495V in normal operation.
ANODE	Ground and Substrate

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## **Absolute Maximum Ratings**

Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These stress ratings only, and functional operation of the device at these or any conditions beyond those indicated under recommended Operating Conditions is not implied. Exposure to "Absolute Maximum Rating" for extended periods may affect device reliability. Use of standard ESD handling precautions is required.

Parameter	Value	Units
CATH Voltage	18	V
REF Current	10	mA
CATH, ANODE Currents	100	mA
Operating Junction Temperature	150	°C
Lead Temperature (soldering 10 seconds)	260	°C
Storage Temperature Range	-65 to +150	°C
ESD Rating (HBM)	3	KV

## **Electrical Specifications**

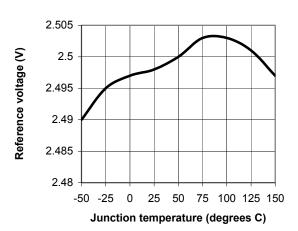
Electrical characteristics are guaranteed over the full temperature range –40°C <Tj<85°C unless otherwise stated. Ambient temperature must be de-rated based upon power dissipation and package thermal characteristics.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
$V_{REF}$	Reference Voltage	25°C; V <sub>REF</sub> =V <sub>CATH</sub> ; I <sub>CATH</sub> =10mA	2.458	2.495	2.532	V
$\Delta V_{REF}$	V <sub>REF</sub> Temperature deviation	−40°C <tj<85°c.< td=""><td></td><td>8</td><td>25</td><td>mV</td></tj<85°c.<>		8	25	mV
$\frac{\Delta V_{REF}}{\Delta V_{CATH}}$	Ratio of V <sub>REF</sub> Change to V <sub>CATH</sub> Change (Line Reg; 1/gain)	I <sub>CATH</sub> =10mA, V <sub>CATH</sub> = V <sub>REF</sub> to 15V		-1	-2.7	mV/V
$I_{REF}$	Reference input current	I <sub>CATH</sub> =10mA		0.7	4	μΑ
$\Delta I_{REF}$	I <sub>REF</sub> Temperature Deviation			0.04	0.2	μΑ
I <sub>CATH(min)</sub>	Minimum Cathode Current			.5	1	mA
I <sub>CATH(OFF)</sub>	Off-State Cathode Current	V <sub>REF</sub> =0V; V <sub>CATH</sub> =15V		.05	1	μA
r <sub>CATH</sub>	Dynamic Output Impedance	I <sub>CATH</sub> =0.1 to 100mA f ≤ 1.0 kHz		0.2	0.5	Ω

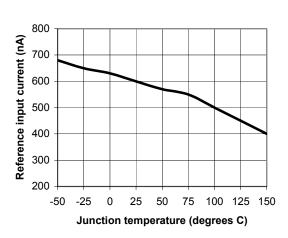
## **Typical Performance Characteristics**

Reference voltage

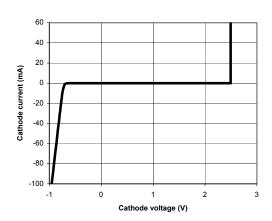
Junction temperature



# Reference input current vs junction temperature

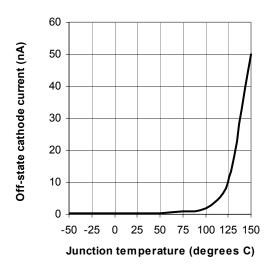


#### Cathode current vs Cathode voltage

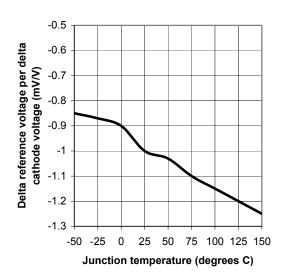


## **Typical Performance Characteristics (contd.)**

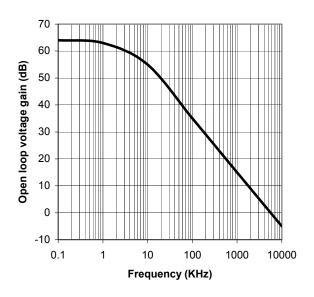
Off-state cathode current vs Junction temperature



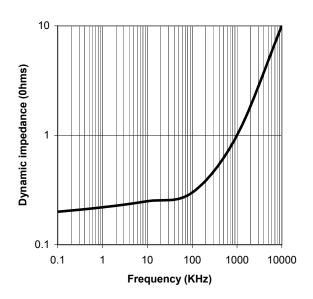
Delta Reference voltage per delta cathode voltage vs junction temperature



Open loop voltage gain vs frequency



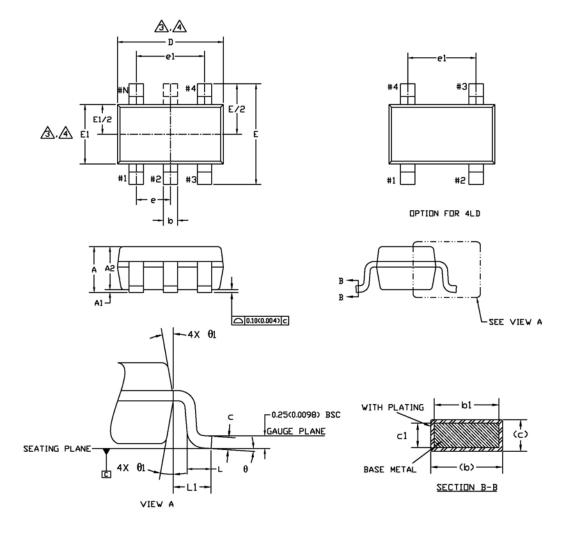
Dynamic impedance vs frequency



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### **Package Dimensions**

## SOT23-3, SOT23-4, SOT23-5, SOT23-6



S	COMMON							
B	DIMENSIONS MILLIMETER			DIMENSIONS INCH				
Ľ	MIN.	N□M. MAX.		MIN.	N□M.	MAX.		
Α	1.20	1.30	1.40	0.047	0.051	0.055		
A1	0.05	-	0.15	0.002	-	0.006		
A2	0.90	1.15	1.30	0.035	0.045	0.051		
b	0.35	-	0.50	0.013	-	0.020		
b1	0.35	0.40	0.45	0.013	0.015	0.017		
С	0.08	- 0.22		0.003	-	0.008		
c1	0.08	0.13	0.20	0.003	0.005	0.007		
ם	2.90 BSC			0.114 BSC				
Ε	2.80 BSC			0.110 BSC				
E1	1.60 BSC			0.062 BSC				
6	0.95 BSC			0.037 BSC				
e1	1.90 BSC		0.074 BSC					
L	0.35	0.45	0.45 0.55		0.017	0.021		
L1	0.60 REF.			0.023 REF.				
θ	0*	4*	8•	0*	4*	8*		
61		10° TYP			10° TYP 10° TYP			P

#### NOTE :

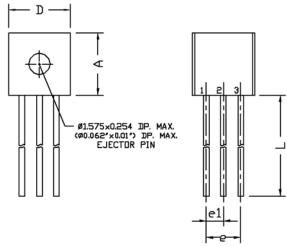
Dimensioning and tolerancing per ASME Y 14.5 M - 1994. Dimensions are in millimeters. Converted inch dimension are not necessarily exact. Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 0.15 mm per side. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.15 mm per side. Top package may be smaller than the bottom package Dimension D and E1 are determine at the outermost extremes of the plastic body exclusive of mold flash gate burrs and interlead flash.

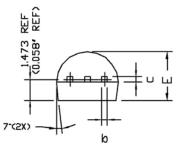
gate burns and interlead flash. Terminal numbers are shown for reference only. Die is facing up for molding. Die is facing down for trim/form.

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## **Package Dimensions**

## TO92-3





Ş	COMMON						
B	DIMENSIONS MILLIMETER			DIMENSIONS INCH			
MIN. NOM. MA		MAX.	MIN.	MAX.			
Α	4.472	4,572	4.672	0.176	0.180	0.184	
b	0.381	0.406	0.431	0.015	0.016	0.017	
c	0.356	0.406	0.456	0.014	0.016	0.018	
D	4.472	4.572	4.672	0.176	0.180	0.184	
Ε	3.456	3.556	3.656	0.136	0.140	0.144	
6	2.413	2.540	2.667	0.095	0.100	0.105	
e1	1.143	1.270	1.397	0.045	0.050	0.055	
L	13.87	13.97	14.07	0.546	0.550	0.554	

#### NDTES :

- 1. CONTROLLING DIMENSION : MILLIMETER. CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT. 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.
- 3. FOR 2 LEAD PACKAGE CENTER LEAD IS CLIPPED

### **Ordering Information**

Device	Operating Tj	%Tol	PKG Type	Vout	Wrap	Ordering Number
LDS431RP	-40C° ≤ 85C°	1.5	TO-92-3	2.5V	BULK	LDS431REX-N3-25-BL
LDS431RP	-40C° ≤ 85C°	1.5	TO-92-3	2.5V	T&R	LDS431REX-N3-25-TL
LDS431RP	-40C° ≤ 85C°	1.5	SOT-23-3	2.5V	T&R	LDS431REX-M3-25-TL

Note: Lead Free and RoHS compliant.

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